

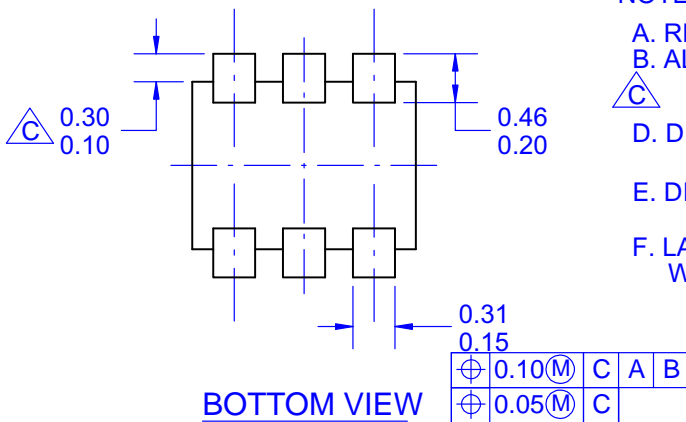
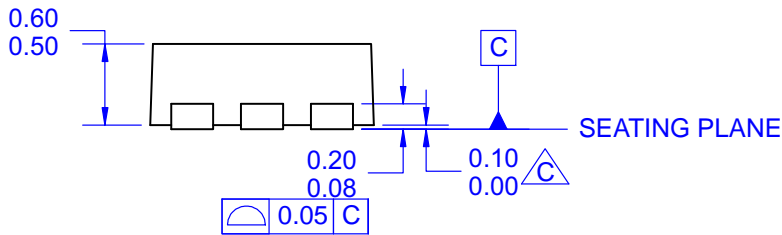
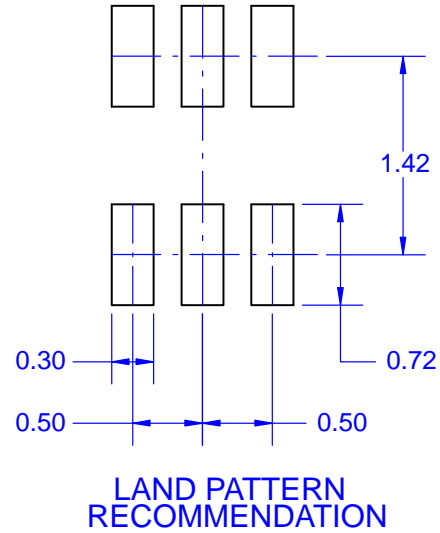
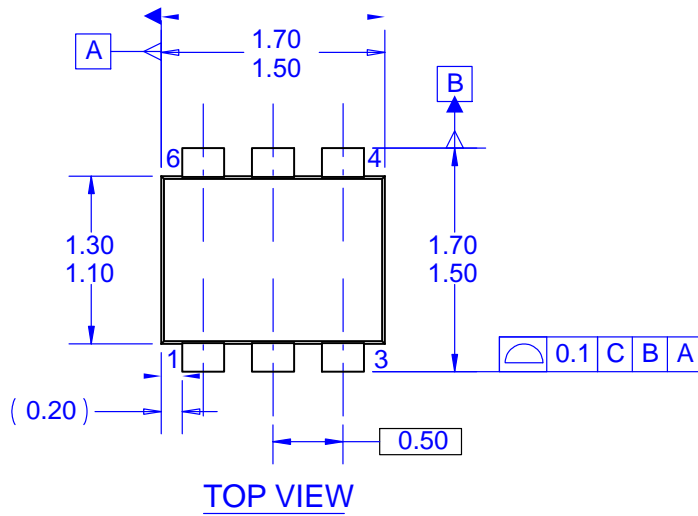
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**SOT-563**  
**CASE 419BH**  
**ISSUE O**

DATE 31 AUG 2016



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. REFERENCE TO JEDEC MO293.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- DOES NOT COMPLY JEDEC STANDARD VALUE.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSION.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- F. LANDPATTERN RECOMMENDATION GENERATED WITH IPC LANDPATTERN GENERATOR

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SOT-563</b>	<b>PAGE 1 OF 2</b>

